



RELIABILITY REPORT  
FOR  
MAX11359AETL+  
PLASTIC ENCAPSULATED DEVICES

July 13, 2009

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
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## Conclusion

The MAX11359AETL+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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## I. Device Description

### A. General

The MAX11359A smart data-acquisition system (DAS) is based on a 16-bit, sigma-delta analog-to-digital converter (ADC) and system-support functionality for a microprocessor ( $\mu$ P)-based system. The device integrates an ADC, DAC, operational amplifiers, internal selectable reference, temperature sensors, analog switches, a 32kHz oscillator, a real-time clock (RTC) with alarm, a high-frequency-locked loop (FLL) clock, four user-programmable I/Os, an interrupt generator, and 1.8V and 2.7V voltage monitors in a single chip.

The MAX11359A has dual 10:1 differential input multiplexers (muxes) that accept signal levels from 0 to AVDD. An on-chip 1x to 8x programmable-gain amplifier (PGA) measures low-level signals and reduces external circuitry required.

The MAX11359A operates from a single +1.8V to +3.6V supply and consumes only 1.4mA in normal mode and only 6.1 $\mu$ A in sleep mode. The MAX11359A has one DAC with two uncommitted op amps.

The serial interface is compatible with either SPI™/QSPI™ or MICROWIRE™, and is used to power up, configure, and check the status of all functional blocks. The MAX11359A is available in a space-saving 40-pin TQFN package and is specified over the commercial (0°C to +70°C) and the extended (-40°C to +85°C) temperature ranges.

## II. Manufacturing Information

A. Description/Function:	Provides a Highly Integrated AFE Offering Higher Accuracy and Lower Cost
B. Process:	S4
C. Number of Device Transistors:	107134
D. Fabrication Location:	California
E. Assembly Location:	China, Thailand
F. Date of Initial Production:	April 25, 2009

## III. Packaging Information

A. Package Type:	40-pin TQFN 6x6
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	38°C/W
K. Single Layer Theta Jc:	1.4°C/W
L. Multi Layer Theta Ja:	27°C/W
M. Multi Layer Theta Jc:	1.4°C/W

## IV. Die Information

A. Dimensions:	126 X 152 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 105 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 10.2 \times 10^{-9}$$

$$\lambda = 10.2 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S4 Process results in a FIT Rate of 0.28 @ 25C and 4.85 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The AC54-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltage per JESD78.

**Table 1**  
Reliability Evaluation Test Results

**MAX11359AETL+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	105	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data